

Call for Papers

ICPT

International Conference on
Planarization/CMP Technology

International Conference on Planarization/CMP Technology 2008 Theme: Frontier of Advanced CMP Technology (ICPT 2008)

November 10-12, 2008

Ambassador Hotel, Hsinchu, Taiwan

Organized by

Chemical Mechanical Planarization User Group Taiwan (CMPUGTW)

Taiwan Society for Abrasive Technology (TSAT)

Industrial Technology Research Institute (ITRI)

National Taiwan University of Science and Technology (NTUST)

In co-operation with

The Japan Society for Precision Engineering, Japanese Planarization and CMP Technical Committee (JSPE)

Korea CMP User Group (KCMPUG)

German CMP User Group (GCMPIUG)

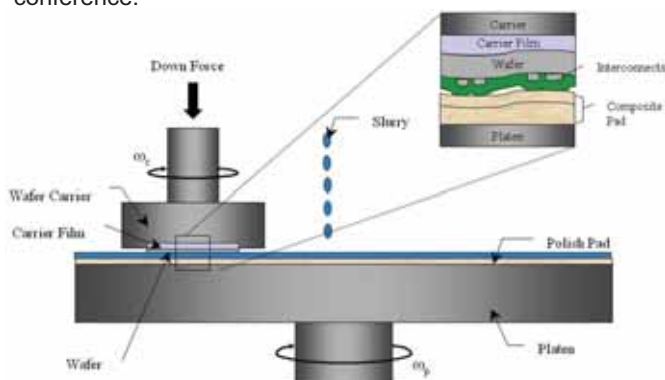
Northern California Chapter AVS (NCCA) CMPUG

Objectives

After successful conferences in Tokyo, Japan (PacRim-CMP 2004), Seoul, Korea (PacRim-CMP 2005), Foster City, California, USA (ICPT 2006) and Dresden, Germany (ICPT 2007), the International Conference on Planarization/CMP Technology (ICPT 2008) will be held on November 10-12, 2008 at Ambassador Hotel, Hsinchu, Taiwan. The objectives of the conference is to provide the international forum for academic researchers, industrial practitioners and engineers from around the world for the exchange of information on state-of-the-art research in CMP technology. ICPT 2008 promotes the exchange of opportunities, ideas, friendly relationships and research collaboration.

Call for papers

We are looking for contributions in the following topics of interest related to CMP technology. Papers in related topics may be submitted for consideration. All papers must be written and submitted in English, the official language for the conference.



Topics

Papers, technical reports, and posters submissions are welcome on a wide range of planarization topics, such as:

- Copper/low-k CMP processes
- Dielectric/STI CMP processes
- Glass CMP
- Non-wafer CMP
- CMP process integration and reliability
- Corrosion control during CMP process
- CMP defects
- Post CMP cleaning
- CMP consumables (conditioners, pads, slurries, post-clean chemicals)
- CMP equipments
- CMP modeling, simulation and theory
- Chemical and physical mechanisms of CMP
- Metrology, characterization and test
- Advanced CMP process control techniques
- Advances in ECD/ECP/ECMP processes and tools
- Low-shear CMP
- CMP in emerging technologies

Submission Guidelines

Abstract (200-500 words)

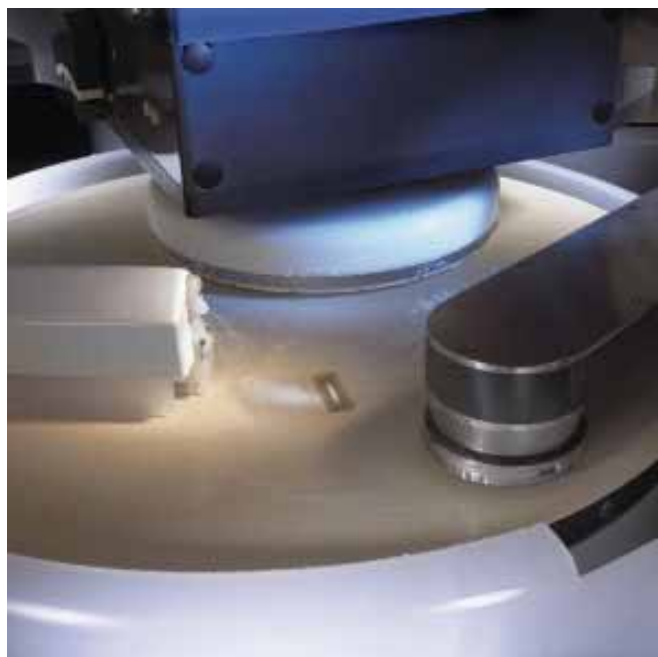
An electronic form (in MS-Word or PDF format) for a succinct, one-page abstract (a minimum of 200 words) with paper title, author names, affiliations, and the corresponding author's phone / fax numbers and e-mail address should be submitted electronically through the conference website at <http://www.icpt2008.itri.org.tw> Please indicate the preference of oral or poster presentation while submitting the abstract.

Paper (4-8 pages)

Camera-ready full-length papers, including figures and references (4-8 pages) for oral presentation should be sent electronically through the conference website upon the notice of accepted abstract. All full papers submission must be in PDF format and submitted electronically through the conference website at <http://www.icpt2008.itri.org.tw> Accepted papers will be published in the Proceedings. Authors presenting accepted papers at the conference must register for the conference.

Poster (1 page)

Posters are for the presentation of projects or research under development or late-breaking results. Poster proposals should consist of a title, an extended abstract, and contact information for the authors. All posters submission must be in PDF format and submitted electronically through the conference website at <http://www.icpt2008.itri.org.tw>. Accepted posters will be displayed at the conference. Abstracts of posters will appear in the conference proceedings.



Registration Information

Full registration

Normal fee: US\$400/ person

Early bird registration fee: US\$350 / person (before 30 Sep. 2008)

Student fee: US\$50 / person

Full registration includes: a banquet, reception, lunches, admission to all conference sessions.

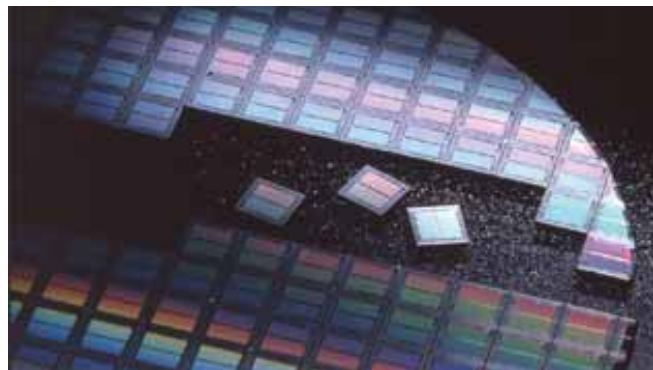
City Tour

Fee: free

All participants (including speakers) are requested to register at <http://www.icpt2008.itri.org.tw>

Important Dates

Abstract due	June 20, 2008
Abstract acceptance notification	July 25, 2008
Receipt of camera ready paper	Sep. 12, 2008
Notification of final acceptance	Sep. 30, 2008



Conference Chairman

Dr. Tsu-An Lin

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Contact

For further information, please check the website:

<http://www.icpt2008.itri.org.tw>

Conference Secretariat

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